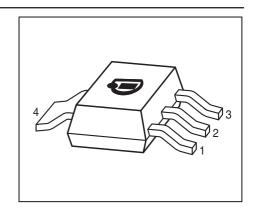


PNP Silicon Darlington Transistor

- High collector current
- Low collector-emitter saturation voltage
- Complementary types: BSP50...BSP52 (NPN)
- Pb-free (RoHS compliant) package
- Qualified according AEC Q101







Туре	Marking	Pin Configuration					Package	
BSP60	BSP60	1=B	2=C	3=E	4=C	-	-	SOT223
BSP61	BSP61	1=B	2=C	3=E	4=C	-	-	SOT223
BSP62	BSP62	1=B	2=C	3=E	4=C	-	-	SOT223

Maximum Ratings

Parameter	Symbol	Value	Unit	
Collector-emitter voltage	V _{CEO}		V	
BSP60		45		
BSP61		60		
BSP62		80		
Collector-base voltage	V _{CBO}			
BSP60		60		
BSP61		80		
BSP62		90		
Emitter-base voltage	V _{EBO}	5		
Collector current	I _C	1	Α	
Peak collector current, $t_p \le 10 \text{ ms}$	I _{CM}	2		
Base current	/ _B	100	mA	
Total power dissipation-	P _{tot}	1.5	W	
<i>T</i> _S ≤ 124 °C				
Junction temperature	$T_{\rm j}$	150	°C	
Storage temperature	$T_{ m stg}$	-65 150		



Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point ¹⁾	R _{thJS}	≤ 17	K/W

Electrical Characteristics at $T_A = 25$ °C, unless otherwise specified

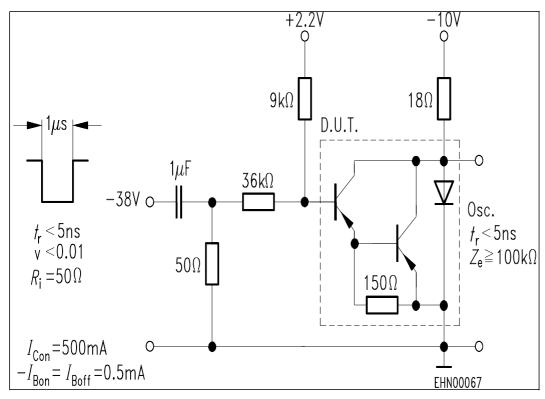
Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics			•	•	•
Collector-emitter breakdown voltage	$V_{(BR)CEO}$				V
$I_{\rm C}$ = 10 mA, $I_{\rm B}$ = 0 , BSP60		45	-	-	
$I_{\rm C}$ = 10 mA, $I_{\rm B}$ = 0 , BSP61		60	-	-	
$I_{\rm C}$ = 10 mA, $I_{\rm B}$ = 0 , BCP62		80	-	-	
Collector-base breakdown voltage	V _{(BR)CBO}				
$I_{\rm C}$ = 100 $\mu{\rm A},I_{\rm E}$ = 0 , BSP60		60	-	-	
$I_{\rm C}$ = 100 $\mu{\rm A},I_{\rm E}$ = 0 , BSP61		80	-	-	
$I_{\rm C}$ = 100 $\mu{\rm A},I_{\rm E}$ = 0 , BSP62		90	-	-	
Emitter-base breakdown voltage	V _{(BR)EBO}	5	-	-	
$I_{\rm E}$ = 100 $\mu {\rm A}, I_{\rm C}$ = 0					
Collector-emitter cutoff current	I _{CES}	-	-	10	μΑ
$V_{\text{CE}} = V_{\text{CE0max}}$, $V_{\text{BE}} = 0$					
Emitter-base cutoff current	I _{EBO}	-	-	10	μA
$V_{EB} = 4 \text{ V}, I_{C} = 0$					
DC current gain ²⁾	h _{FE}				-
$I_{\rm C}$ = 150 mA, $V_{\rm CE}$ = 10 V		1000	-	-	
$I_{\rm C}$ = 500 mA, $V_{\rm CE}$ = 10 V		2000	-	-	
Collector-emitter saturation voltage ²⁾	V _{CEsat}				V
$I_{\rm C}$ = 500 mA, $I_{\rm B}$ = 0.55 mA		-	-	1.3	
$I_{\rm C}$ = 1 A, $I_{\rm B}$ = 1 mA		-	-	1.8	
Base emitter saturation voltage ²⁾	V _{BEsat}				
$I_{\rm C}$ = 500 mA, $I_{\rm B}$ = 0.5 mA		-	-	1.9	
$I_{\rm C}$ = 1 A, $I_{\rm B}$ = 1 mA		-	-	2.2	
AC Characteristics	<u> </u>				
Transition frequency	f_{T}	-	200	-	MHz
$I_{\rm C}$ = 100 mA, $V_{\rm CE}$ = 5 V, f = 100 MHz					

 $^{^{1}}$ For calculation of R_{thJA} please refer to Application Note AN077 (Thermal Resistance Calculation)

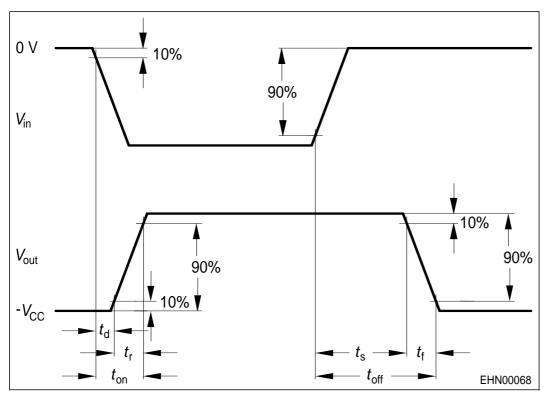
 $^{^{2}}$ Pulse test: t < 300µs; D < 2%



Switching time test circuit



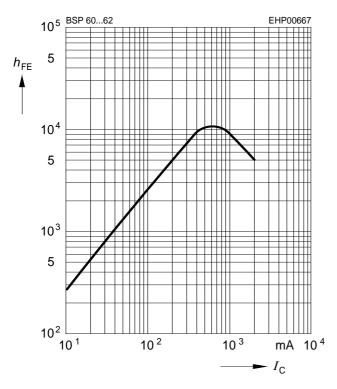
Switching time waveform





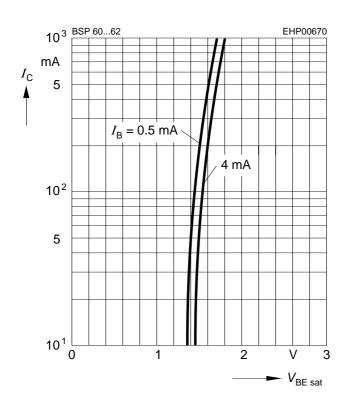
DC current gain $h_{FE} = f(I_C)$

$$V_{CE}$$
 = 10 V



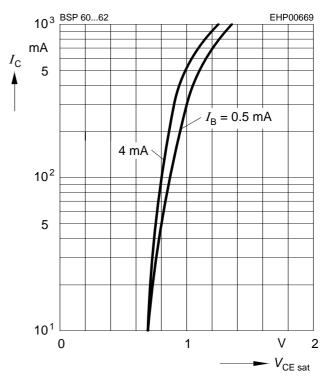
Base-emitter saturation voltage

$$I_{C} = f(V_{BEsat}), I_{B} = Parameter$$



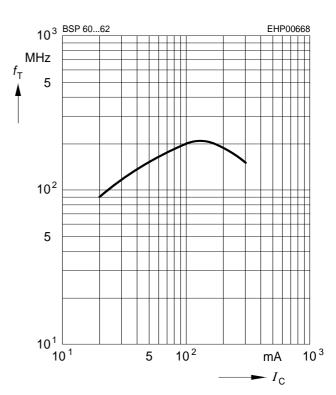
Collector-emitter saturation voltage

 $I_{C} = f(V_{CEsat}), I_{B} = Parameter$



Transition frequency $f_T = f(I_C)$

$$V_{CE} = 10 \text{ V}, f = 100 \text{ MHz}$$

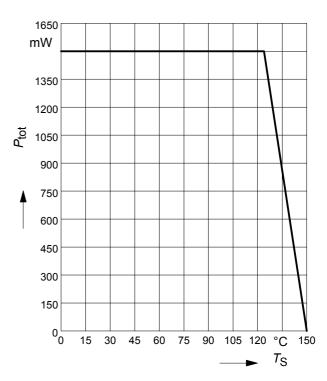




Collector-base capacitance $C_{cb} = f(V_{CB})$ Emitter-base capacitance $C_{eb} = f(V_{EB})$

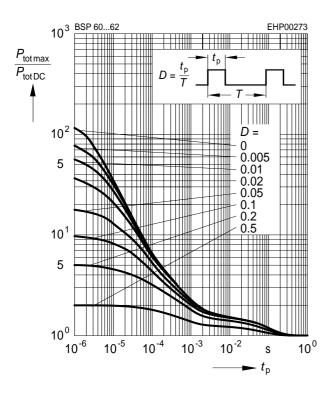
22 pF CEB 18 18 16 10 8 6 4 20 4 8 12 16 VCB(VEB

Total power dissipation $P_{tot} = f(T_S)$



Permissible Pulse Load

 $P_{\text{totmax}}/P_{\text{totDC}} = f(t_{p})$

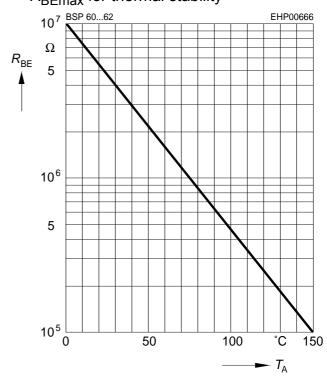


External resistance $R_{BE} = f (T_A)^{**}$

 $V_{CB} = V_{CEmax}$

5

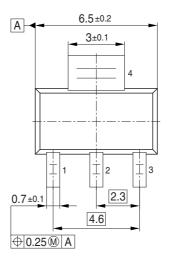
** R_{BEmax} for thermal stability

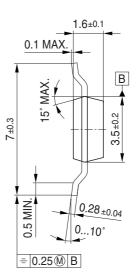




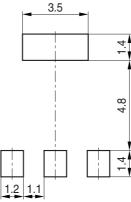
Package Outline



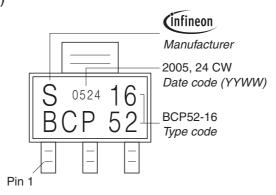




Foot Print

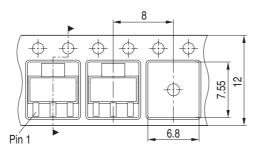


Marking Layout (Example)



Packing

Reel ø180 mm = 1.000 Pieces/Reel Reel ø330 mm = 4.000 Pieces/Reel







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